Non-invasive backside detection of waveforms/logic within a die using a CW laser

- FFT Frequency Mapping to quickly trace signal paths inside a die

- Best-in-class:
  - Resolution with Centric and Aplanatic RSILs
  - Bandwidth up to 12 GHz
  - Test loop lengths up to 1000 ms
  - Measure rise times < 40 ps

- Optional:
  - SOM with 1064 nm and 1340 nm lasers
  - PEM with ultra low-noise InGaAs camera (LN₂ or TE cooled)

- Device Thermal Control